

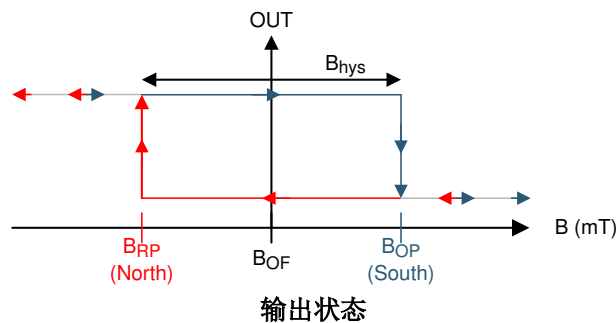
TMAG5115 高速、低抖动霍尔效应锁存器

1 特性

- 高速数字双极锁存霍尔传感器
 - 低传播延迟：5 μ s
 - 低抖动：5 μ s
 - 带宽 (BW)：60kHz
- 支持宽电压范围：
 - 2.5V 至 26V
 - 无需外部稳压器
- 快速开通时间：62.5 μ s
- 高精度阈值：
 - ± 3 mT (最大变化为 ± 1 mT)
 - ± 1 mT (最大变化为 ± 0.7 mT)
- 保护特性：
 - 输出短路保护
 - 输出电流限制
 - 过热保护
- 开漏输出 (15mA 灌电流)
- 宽工作温度范围：
 - 40°C 至 125°C
- 小型封装和外形尺寸：
 - 表面贴装 3 引脚 SOT-23
 - 2.92mm $\times$ 2.37mm

2 应用

- 无线电动工具
- 扫地机器人
- 计算机风扇
- 阀和电磁阀状态
- 工业无刷直流电机



3 说明

TMAG5115 器件是一款高性能霍尔效应锁存传感器，具有快速传播延迟和低抖动。该器件还在整个温度范围内具有高灵敏度稳定性，并为需要高 RPM 的应用提供了集成保护功能。低抖动和低传播延迟相结合有助于提高功效并降低系统级寄生噪声。

该器件配有一个灌电流能力达 15mA 的开漏输出级。TMAG5115 具有 2.5V 至 26V 的宽工作电压范围，专为各种工业和商业应用而设计。针对输出短路、过流和过热情况提供内部保护功能。

TMAG5115 采用业界通用的 SOT-23 封装。

封装信息 (1)

器件型号	封装	封装尺寸(2)
TMAG5115	DBZ (SOT-23 , 3)	2.92mm $\times$ 2.37mm

(1) 有关所有可用封装，请参阅节 11。

(2) 封装尺寸 (长 $\times$ 宽) 为标称值，并包括引脚 (如适用)。

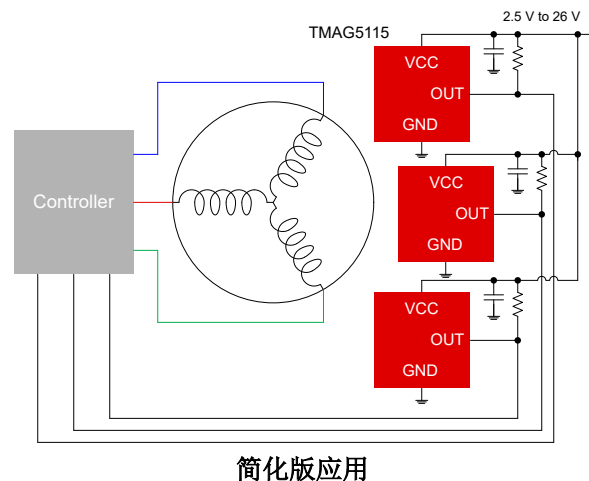


Table of Contents

1 特性	1	7.4 Device Functional Modes.....	14
2 应用	1	8 Application and Implementation	15
3 说明	1	8.1 Application Information.....	15
4 Device Comparison	3	8.2 Typical Applications.....	15
5 Pin Configuration and Functions	3	8.3 Power Supply Recommendations.....	18
6 Specifications	4	8.4 Layout.....	18
6.1 Absolute Maximum Ratings.....	4	9 Device and Documentation Support	19
6.2 ESD Ratings.....	4	9.1 Device Support.....	19
6.3 Recommended Operating Conditions.....	4	9.2 接收文档更新通知.....	19
6.4 Thermal Information.....	4	9.3 支持资源.....	19
6.5 Electrical Characteristics.....	5	9.4 Trademarks.....	19
6.6 Magnetic Characteristics.....	5	9.5 静电放电警告.....	19
6.7 Typical Characteristics.....	6	9.6 术语表.....	19
7 Detailed Description	8	10 Revision History	20
7.1 Overview.....	8	11 Mechanical, Packaging, and Orderable	
7.2 Functional Block Diagram.....	8	Information	20
7.3 Feature Description.....	9		

4 Device Comparison

表 4-1. Device Comparison

VERSION	TYPICAL THRESHOLD	TYPICAL HYSTERESIS	MAGNETIC RESPONSE	OUTPUT TYPE	SENSOR ORIENTATION	BANDWIDTH	PACKAGES AVAILABLE
TMAG5115A1C	1 mT	2 mT	Active Low	Open-drain	Z	60 kHz	SOT-23
TMAG5115B1C	3 mT	6 mT	Active Low	Open-drain	Z	60 kHz	SOT-23

5 Pin Configuration and Functions

For additional configuration information, see the [Mechanical, Packaging, and Orderable Information](#) section.

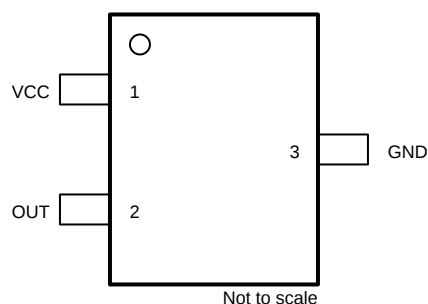


图 5-1. DBZ Package 3-Pin SOT-23 Top View

表 5-1. Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
GND	3	GND	Ground pin
OUT	2	O	Hall sensor open-drain output. Requires a resistor pullup, typically 10 k Ω .
V _{CC}	1	P	Supply pin. 2.5 V to 26 V. TI recommends to use a minimum 0.01- μ F capacitor.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Power supply voltage	– 0.3	30	V
I _{SINK}	Output sink current		30	mA
Magnetic flux density, B _{MAX}		Unlimited	Unlimited	T
Junction temperature, T _J		– 65	150	°C
Storage temperature, T _{stg}		– 65	150	°C

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.

6.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
		Charged device model (CDM), ANSI/ESDA/JEDEC JS-002 ⁽²⁾	±500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
 (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CC}	Power supply voltage ⁽¹⁾	2.5	26	V
V _O	Output pin voltage	0	26	V
I _{SINK}	Output pin current sink	0	15	mA
T _A	Ambient temperature	– 40	125	°C

- (1) Operating outside the [TMAG5115 Recommended Supply and Temperature Curve](#) can cause the device to enter a thermal shutdown state.

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TMAG5115	UNIT
		DBZ (SOT-23)	
		3 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	208.2	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	102.3	°C/W
R _{θJB}	Junction-to-board thermal resistance	40.6	°C/W
Ψ _{JT}	Junction-to-top characterization parameter	9.7	°C/W
Ψ _{JB}	Junction-to-board characterization parameter	40.2	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	–	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

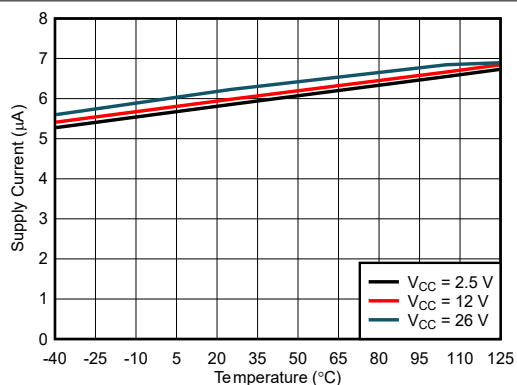
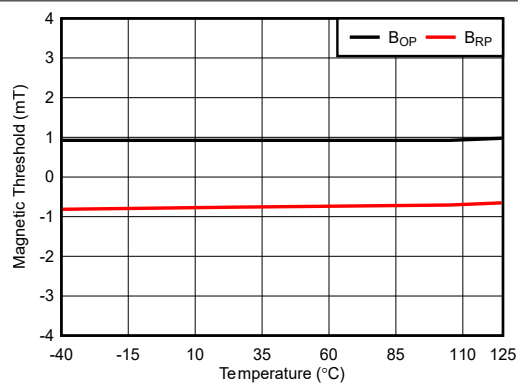
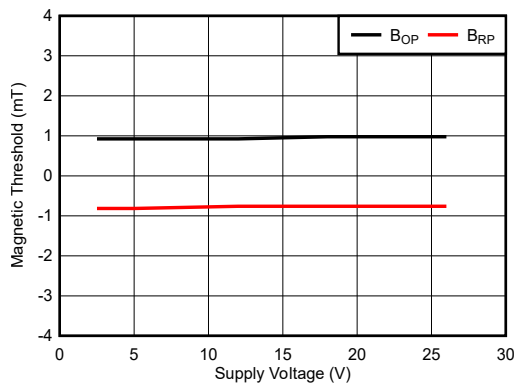
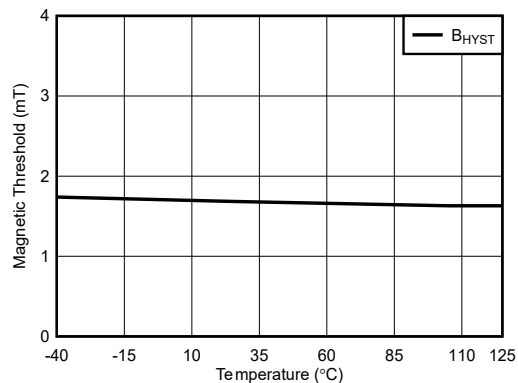
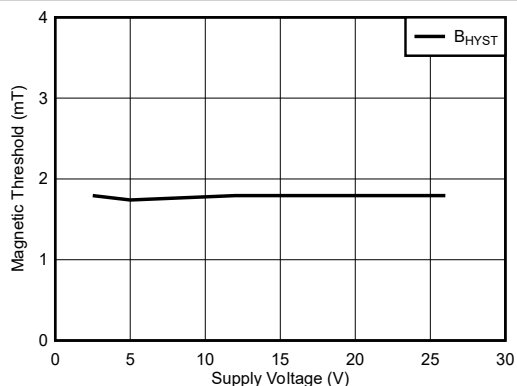
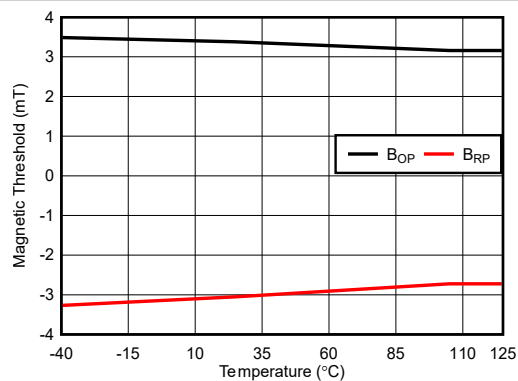
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SUPPLY						
I_{CC}	Operating supply current	$V_{CC} = 2.5\text{ V to }26\text{ V}$ $T_A = -40^\circ\text{C to }125^\circ\text{C}$		6	8	mA
t_{ON}	Power-on time			62.5		μs
P_{OS}	Power-on state	$V_{CC} > V_{CCmin}$ $t < t_{ON}$		High		
OUTPUT						
V_{OL}	Low-level output voltage	$I_{OL} = 5\text{ mA}$	0		0.7	V
I_{OH}	Output leakage current	$V_{CC} = 2.5\text{ V to }26\text{ V}$		0.1	1	μA
I_{SC}	Output short-circuit current protection		15	25	80	mA
t_R	Output rise time	$R_L = 10\text{ k}\Omega$ $C_L = 50\text{ pF}$ $V_{CC} = 12\text{ V}$		2		μs
t_F	Output fall time	$R_L = 10\text{ k}\Omega$ $C_L = 50\text{ pF}$ $V_{CC} = 12\text{ V}$		2		μs
t_{PD}	Propagation delay time			5	6	μs
Jitter	Output jitter window	1-kHz triangle magnetic wave with peak value at $\pm 8\text{ mT}$		5		μs
Jitter	Output jitter window	1-kHz square magnetic wave with peak value at $\pm 8\text{ mT}$		0.2		μs
Noise _{pp}	Internal Noise			125	200	μT
T_{SHUT}	Junction temperature shutdown threshold		156	168	180	$^\circ\text{C}$
T_{REC}	Junction temperature recovery threshold		131	143	155	$^\circ\text{C}$
FREQUENCY RESPONSE						
f_{CHOP}	Chopping frequency	TMAG5115xx		1000		kHz
f_{BW}	Signal bandwidth	TMAG5115xx		60		kHz

6.6 Magnetic Characteristics

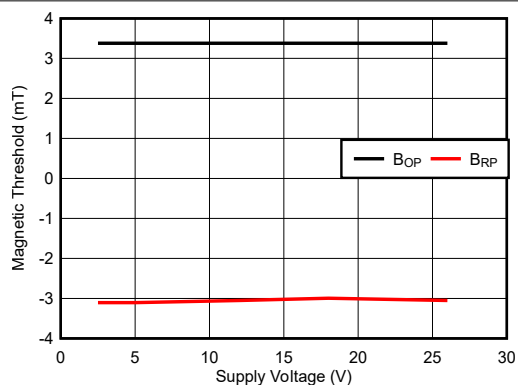
over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
TMAG5115A						
B _{OP}	Magnetic field operating point	V _{CC} = 2.5 V to 26 V	0.2	1	1.7	mT
B _{RP}	Magnetic field release point		- 1.7	- 1	- 0.2	mT
B _{HYS}	Magnetic hysteresis B _{OP} - B _{RP}		0.4	2	3.4	mT
TMAG5115B						
B _{OP}	Magnetic field operating point	V _{CC} = 2.5 V to 26 V	2	3	4	mT
B _{RP}	Magnetic field release point		- 4	- 3	- 2	mT
B _{HYS}	Magnetic hysteresis B _{OP} - B _{RP}		4	6	8	mT

6.7 Typical Characteristics

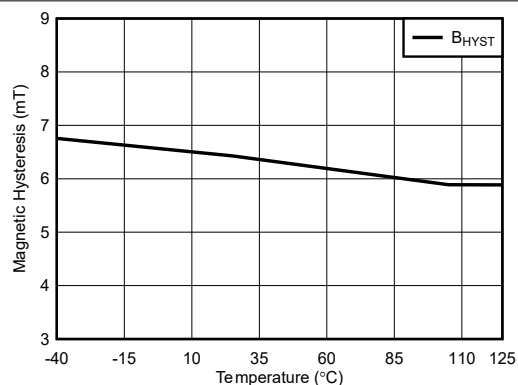
图 6-1. I_{CC} vs T_A  $V_{CC} = 12 V$ 图 6-2. TMAG5115A B_{OP} and B_{RP} vs T_A  $T_A = 25^{\circ}C$ 图 6-3. TMAG5115A B_{OP} and B_{RP} vs V_{CC}  $V_{CC} = 12 V$ 图 6-4. TMAG5115A B_{HYST} vs T_A  $T_A = 25^{\circ}C$ 图 6-5. TMAG5115A B_{HYST} vs V_{CC}  $V_{CC} = 12 V$ 图 6-6. TMAG5115B B_{OP} and B_{RP} vs T_A

6.7 Typical Characteristics (continued)



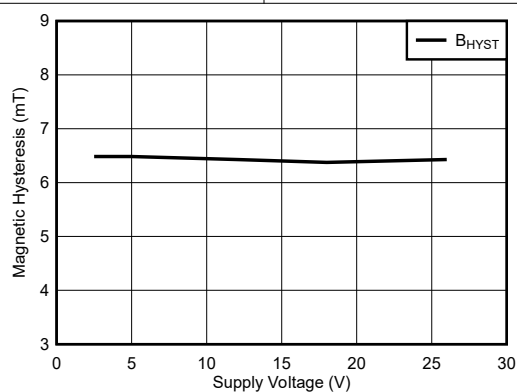
$T_A = 25^\circ\text{C}$

图 6-7. TMAG5115B B_{OP} and B_{RP} vs V_{CC}



$V_{CC} = 12\text{ V}$

图 6-8. TMAG5115B B_{HYST} vs T_A



$T_A = 25^\circ\text{C}$

图 6-9. TMAG5115B B_{HYST} vs V_{CC}

7 Detailed Description

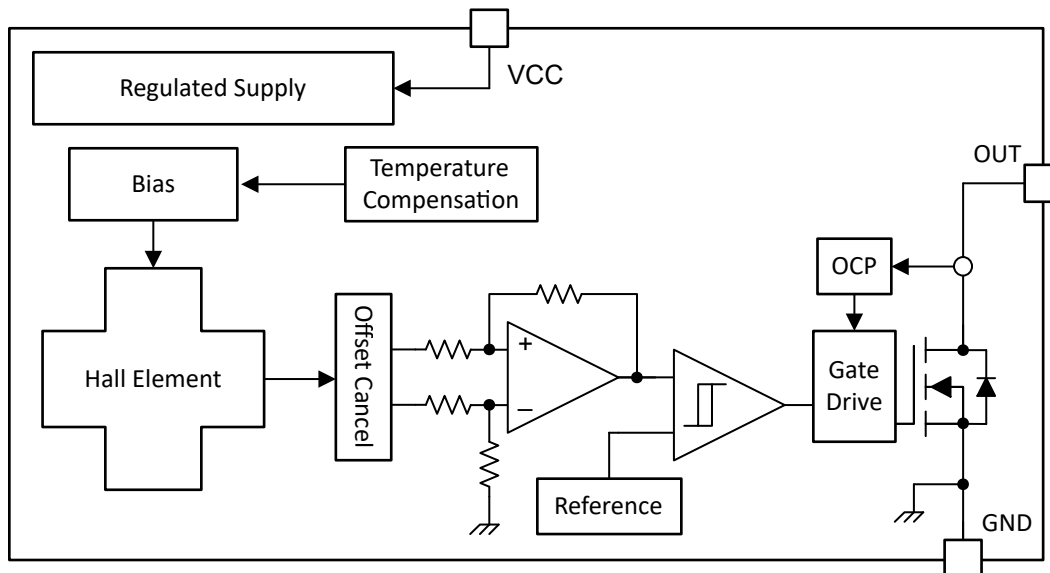
7.1 Overview

The TMAG5115 is a chopper-stabilized Hall sensor with a digital latched output for magnetic sensing applications. The TMAG5115 device can be powered with a supply voltage between 2.5 V and 26 V. The field polarity is defined as follows: a south pole near the marked side of the package is a positive magnetic field, and a north pole near the marked side of the package is a negative magnetic field.

The output state is dependent on the magnetic field perpendicular to the package. A south pole near the marked side of the package causes the output to pull low (operate point, B_{OP}), and a north pole near the marked side of the package causes the output to release (release point, B_{RP}). Hysteresis is included in between the operate point and the release point therefore magnetic-field noise does not accidentally trip the output.

An external pullup resistor is required on the OUT pin. The OUT pin can be pulled up to V_{CC} or to a different voltage supply to allow for easier interfacing with controller circuits.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Field Direction Definition

图 7-1 shows the positive magnetic field defined as a south pole near the marked side of the package and the negative magnetic field defined as a north pole near the marked side of the package.

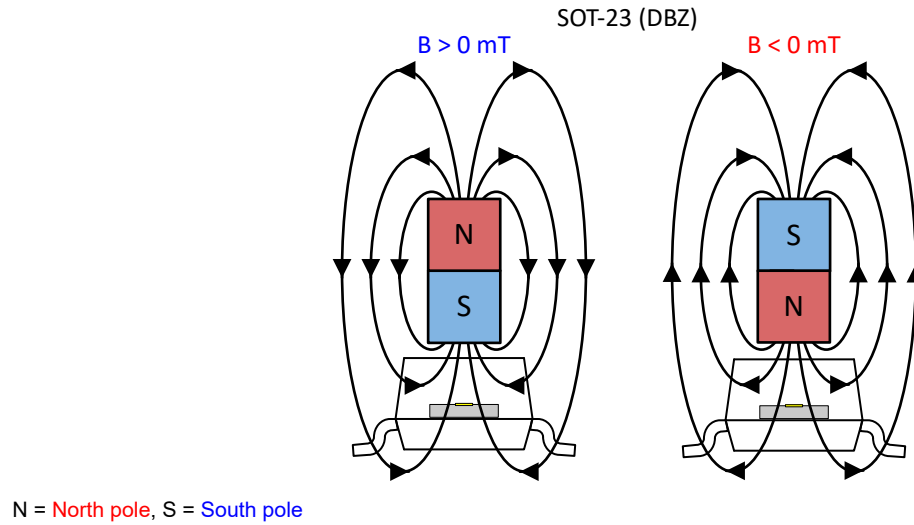


图 7-1. Field Direction Definition

7.3.2 Device Output

If the device is powered on with a magnetic field strength between B_{RP} and B_{OP} , then the device output is indeterminate and can either be Hi-Z or low. If the field strength is greater than B_{OP} , then the output is pulled low. If the field strength is less than B_{RP} , then the output is released.

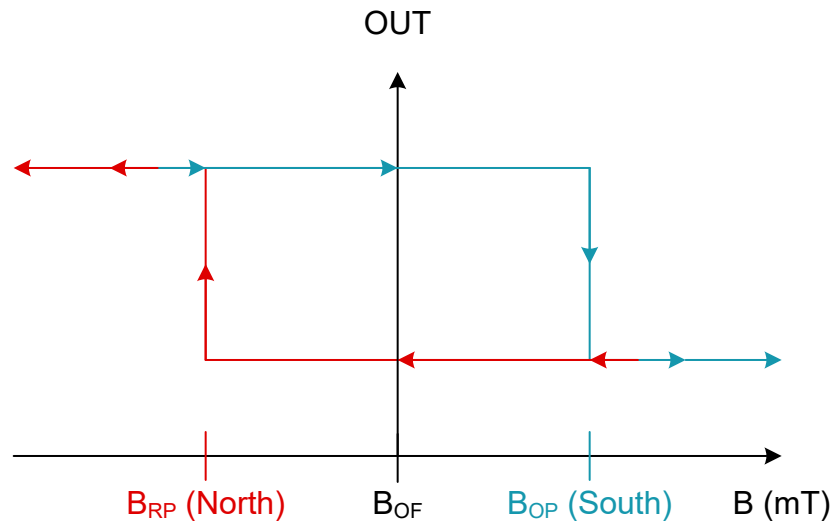


图 7-2. TMAG5115 $B_{OP} > 0$

7.3.3 Power-On Time

After applying V_{CC} to the TMAG5115, t_{on} must elapse before the OUT pin is valid. During the power-up sequence, the output is Hi-Z. A pulse as shown in 图 7-3 and 图 7-4 occurs at the end of t_{on} . This pulse can allow the host processor to determine when the TMAG5115 output is valid after start-up. In Case 1 (图 7-3) and Case 2 (图 7-4), the output is defined assuming a constant magnetic field $B > B_{OP}$ and $B < B_{RP}$.

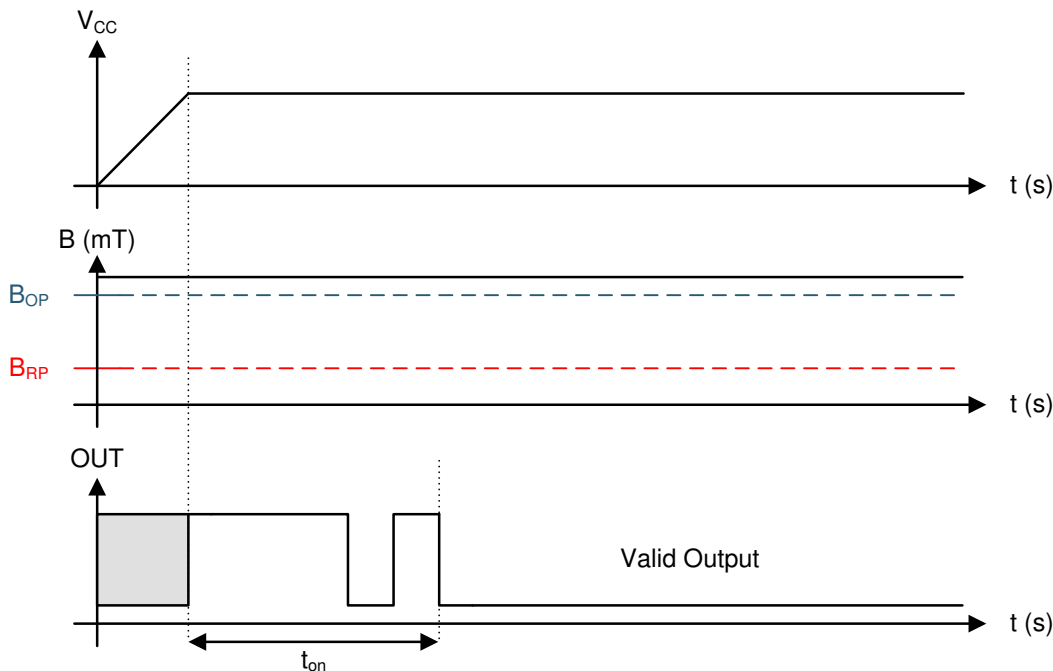


图 7-3. Case 1: Power On When $B > B_{OP}$

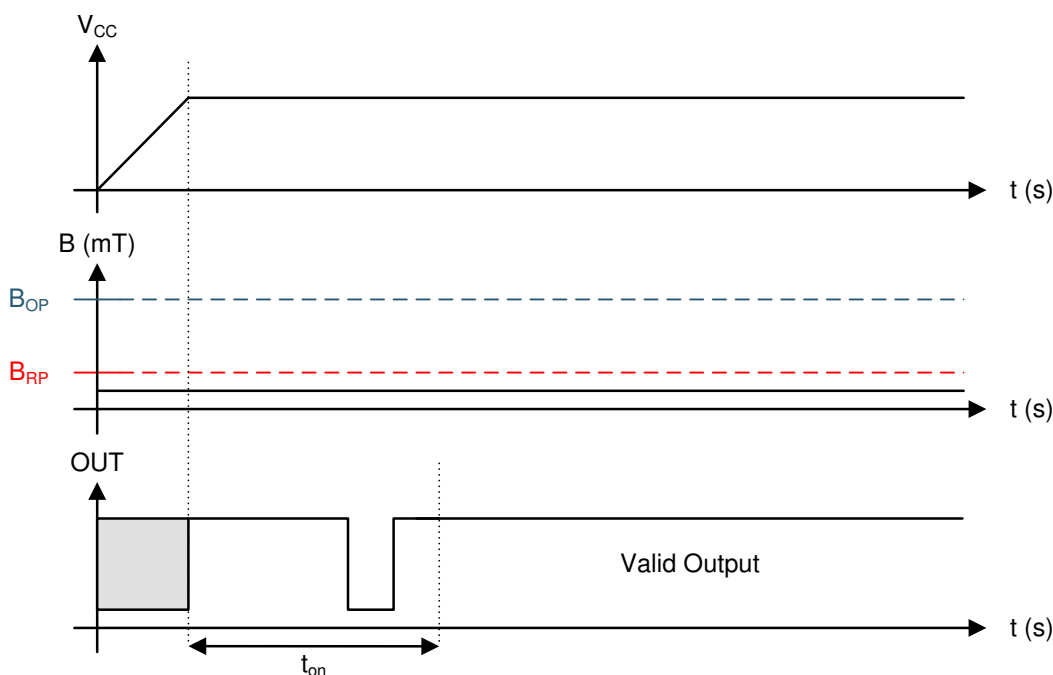


图 7-4. Case 2: Power On When $B < B_{RP}$

If the device is powered on with the magnetic field strength $B_{RP} < B < B_{OP}$, then the device output is indeterminate and can either be Hi-Z or pulled low. During the power-up sequence, the output is held Hi-Z until t_{on} has elapsed. At the end of t_{on} , a pulse is given on the OUT pin to indicate that t_{on} has elapsed. After t_{on} , if the magnetic field changes such that $B_{OP} < B$, the output is released. Case 3 (图 7-5) and Case 4 (图 7-6) show examples of this behavior.

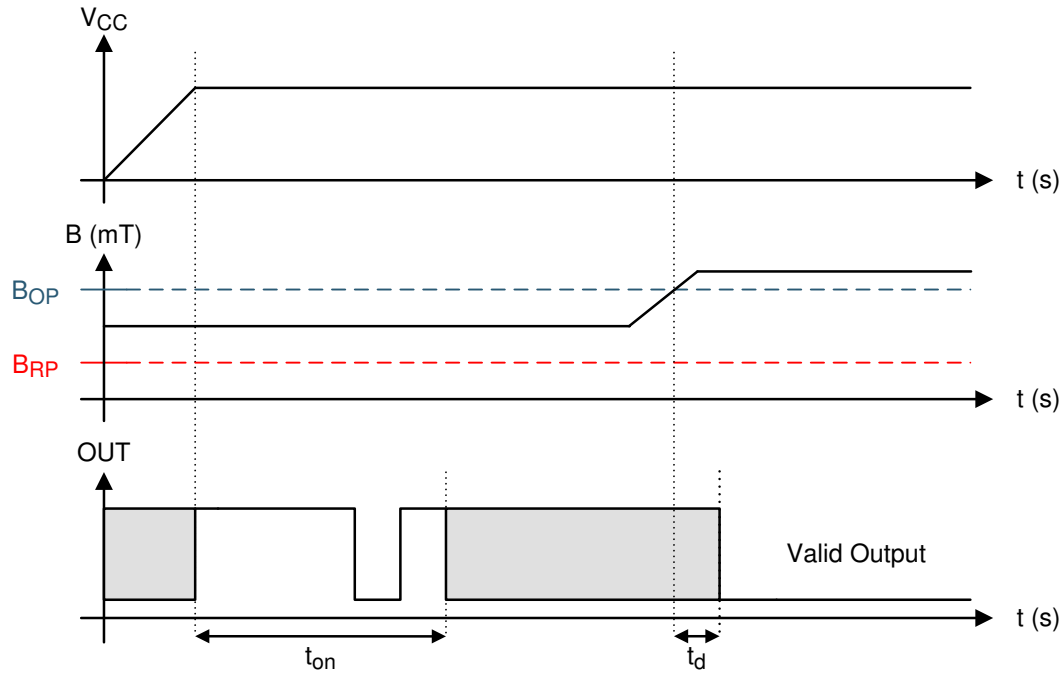


图 7-5. Case 3: Power On When $B_{RP} < B < B_{OP}$, Followed by $B > B_{OP}$

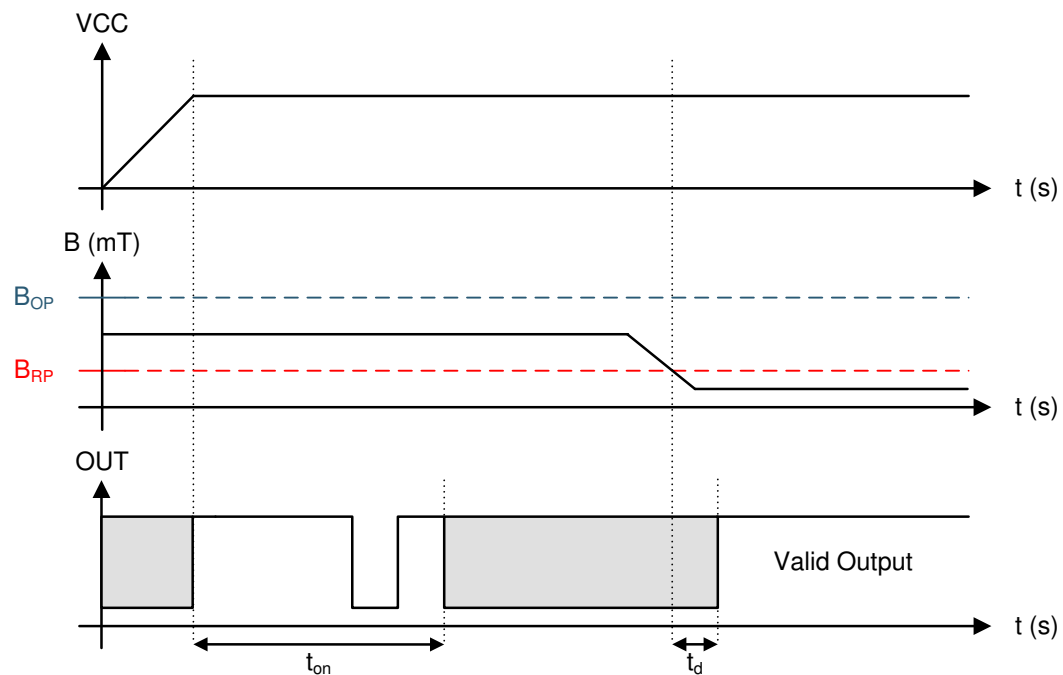


图 7-6. Case 4: Power On When $B_{RP} < B < B_{OP}$, Followed by $B < B_{RP}$

7.3.4 Output Stage

图 7-7 shows the TMAG5115 open-drain NMOS output structure, rated to sink up to 15 mA of current.

备注

V_{ref} is not restricted to V_{CC} . The allowable voltage range of this pin is specified in the [Recommended Operating Conditions](#).

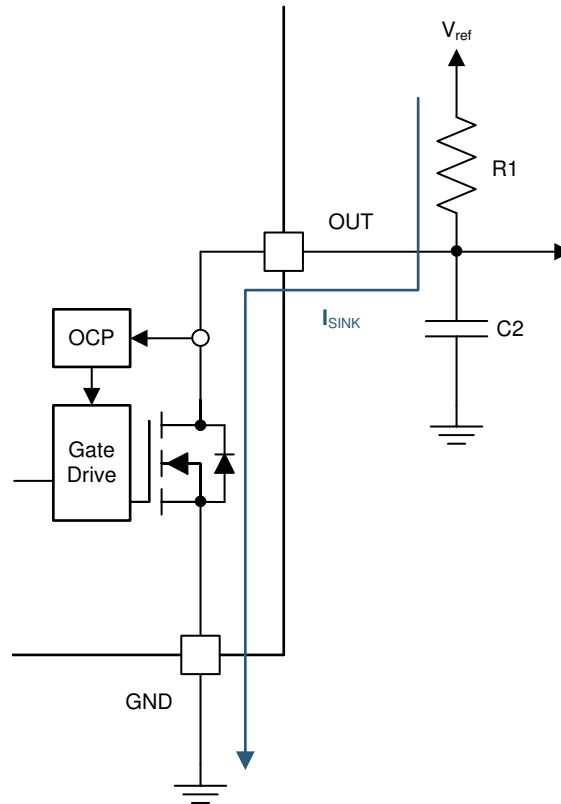


图 7-7. NMOS Open-Drain Output

Select a value for C2 based on the system bandwidth specifications as shown in [方程式 1](#).

$$2 \times f_{BW} \text{ (Hz)} < \frac{1}{2\pi \times R1 \times C2} \quad (1)$$

Most applications do not require this C2 filtering capacitor.

7.3.5 Protection Circuits

The TMAG5115 device is fully protected against overcurrent and overtemperature conditions. 表 7-1 lists a summary of the protection circuits.

表 7-1. Protection Circuit Summary

FAULT	CONDITION	DEVICE	DESCRIPTION	RECOVERY
FET overload	$I_{SINK} \geq I_{SC}$	Operating	Output current is clamped to I_{SC}	$I_{SINK} < I_{SC}$
Overtemperature	$T_J \geq 156^{\circ}\text{C}$	Operating	Device shuts down until recovery temperature is reached	$T_J \leq 156^{\circ}\text{C}$

7.3.5.1 Short-Circuit Protection

An analog current-limit circuit limits the current through the FET. The driver current is clamped to I_{SC} . During this clamping, the $r_{DS(on)}$ of the output FET is increased from the nominal value.

7.3.5.2 Overtemperature Protection

The TMAG5115 features overtemperature protection to prevent damage to the device and system in the case of runaway thermal heating. If the output is short-circuited, there will be greater power dissipation through the device causing the junction temperature to rise. If the temperature rises to above the limits specified in the [Electrical Characteristics](#) table, the device will enter a thermal shutdown and the OUT pin will turn to Hi-Z regardless of the current magnetic field detected.

The TMAG5115 thermal shutdown can be differentiated from normal operation by viewing the supply current into the device. While in thermal shutdown, the supply current is lower than normal operation.

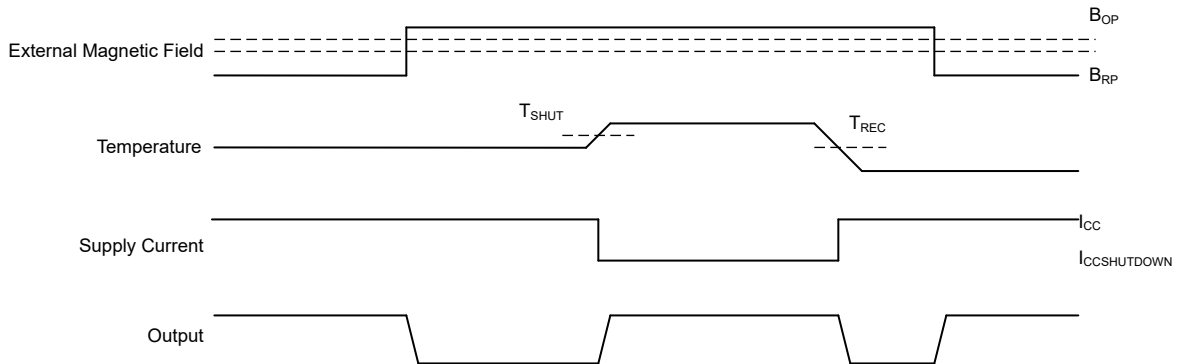


图 7-8. TMAG5115 Overtemperature Protection Diagram

The TMAG5115 can support a supply voltage of 2.5 V to 26 V. Higher temperature and supply conditions can increase the junction temperature of the device, however, which can exceed the thermal shutdown limit. This can cause a device shutdown. TI recommends to not exceed a temperature and supply combination shown in 图 7-9.

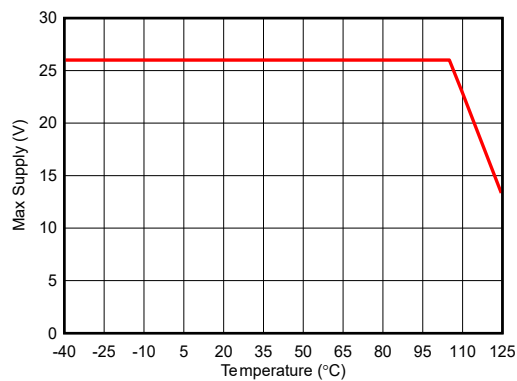


图 7-9. TMAG5115 Recommended Supply and Temperature Curve

7.4 Device Functional Modes

The TMAG5115 is active only when V_{CC} is between 2.5 V and 26 V and T_J is less than 156°C.

8 Application and Implementation

备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

The TMAG5115 is used in magnetic position sensing applications. The device features a high-speed architecture to facilitate precise field measurement. With latching magnetic characteristics, the output is turned low or high respectively with a sufficiently strong south or north pole facing the package top side. When removing the magnetic field, the device keeps its previous state.

For reliable functionality, the magnet must apply a flux density at the sensor greater than the corresponding maximum B_{OP} or B_{RP} numbers specified in the [Magnetic Characteristics](#) table. Add additional margin to account for mechanical tolerance, temperature effects, and magnet variation.

8.2 Typical Applications

8.2.1 Standard Circuit

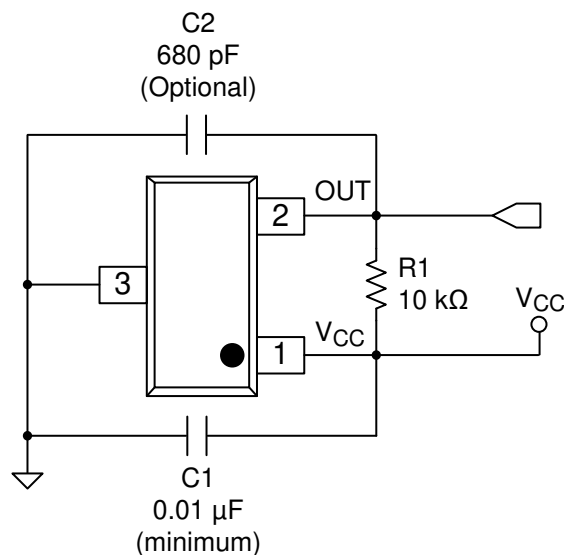


图 8-1. Typical Application Circuit

8.2.1.1 Design Requirements

For this design example, use the parameters listed in [表 8-1](#) as the input parameters.

表 8-1. Design Parameters

DESIGN PARAMETER	REFERENCE	EXAMPLE VALUE
Supply voltage	V_{CC}	3.0 V to 3.6 V
System bandwidth	f_{BW}	10 kHz

8.2.1.2 Detailed Design Procedure

表 8-2. External Components

COMPONENT	PIN 1	PIN 2	RECOMMENDED
C1	V _{CC}	GND	A 0.01-μF (minimum) ceramic capacitor rated for V _{CC}
C2	OUT	GND	Optional: Place a ceramic capacitor to GND
R1	OUT	REF ⁽¹⁾	Requires a resistor pullup

(1) REF is not a pin on the TMAG5115 device, but a REF supply-voltage pullup is required for the OUT pin. The OUT pin may be pulled up to V_{CC}.

8.2.1.2.1 Configuration Example

In a 3.3-V system, $3.0\text{ V} \leq V_{\text{ref}} \leq 3.6\text{ V}$. Use 方程式 2 to calculate the allowable range for R1.

$$\frac{V_{\text{ref max}}}{30\text{ mA}} \leq R1 \leq \frac{V_{\text{ref min}}}{100\text{ }\mu\text{A}} \quad (2)$$

For this design example, use 方程式 3 to calculate the allowable range of R1.

$$\frac{3.4\text{ V}}{30\text{ mA}} \leq R1 \leq \frac{3.2\text{ V}}{100\text{ }\mu\text{A}} \quad (3)$$

Therefore:

$$120\text{ }\Omega \leq R1 \leq 30\text{ k}\Omega \quad (4)$$

After finding the allowable range of R1 (方程式 4), select a value between 500 Ω and 32 kΩ for R1.

Assuming a system bandwidth of 10 kHz, use 方程式 5 to calculate the value of C2.

$$2 \times f_{\text{BW}} (\text{Hz}) < \frac{1}{2\pi \times R1 \times C2} \quad (5)$$

For this design example, use 方程式 6 to calculate the value of C2.

$$2 \times 10\text{ kHz} < \frac{1}{2\pi \times R1 \times C2} \quad (6)$$

An R1 value of 10 kΩ and a C2 value less than 820 pF satisfy the requirement for a 10-kHz system bandwidth.

A selection of R1 = 10 kΩ and C2 = 680 pF can cause a low-pass filter with a corner frequency of 23.4 kHz.

8.2.1.3 Application Curves

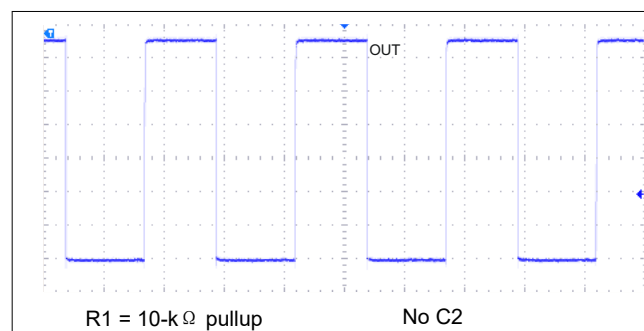


图 8-2. 10-kHz Switching Magnetic Field

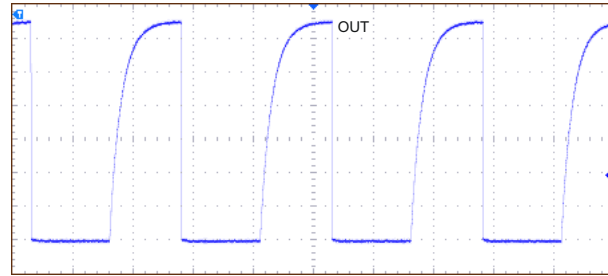


图 8-3. 10-kHz Switching Magnetic Field

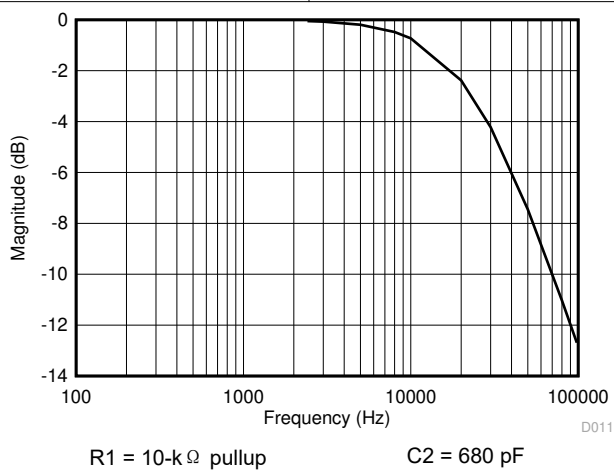


图 8-4. Low-Pass Filtering

8.3 Power Supply Recommendations

The TMAG5115 device is designed to operate from an input voltage supply range between 2.5 V and 26 V. A recommended 0.1- μ F ceramic capacitor rated for V_{CC} must be placed as close to the TMAG5115 as possible. Bypass capacitor values larger than 0.1 μ F may be required to attenuate any significant high-frequency ripple and noise components generated by the power source. TI recommends limiting the supply voltage variation to less than 50 mV_{PP}.

8.4 Layout

8.4.1 Layout Guidelines

TI recommends placing the bypass capacitor near the TMAG5115 device for efficient power delivery with minimal inductance. TI recommends placing the external pullup resistor near the microcontroller input to provide the most stable voltage at the input. Alternatively, an integrated pullup resistor within the GPIO of the microcontroller can be used.

Generally, using PCB copper planes underneath the TMAG5115 device has no effect on magnetic flux and does not interfere with device performance. This is because copper is not a ferromagnetic material. However, nearby system components that contain iron or nickel can redirect magnetic flux in unpredictable ways.

8.4.2 Layout Example

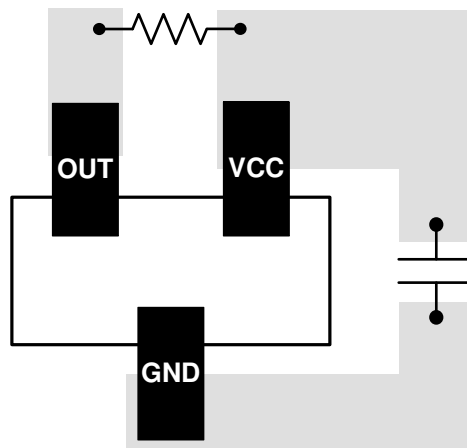


图 8-5. TMAG5115 Layout Example

9 Device and Documentation Support

9.1 Device Support

9.1.1 Hall Sensor Location

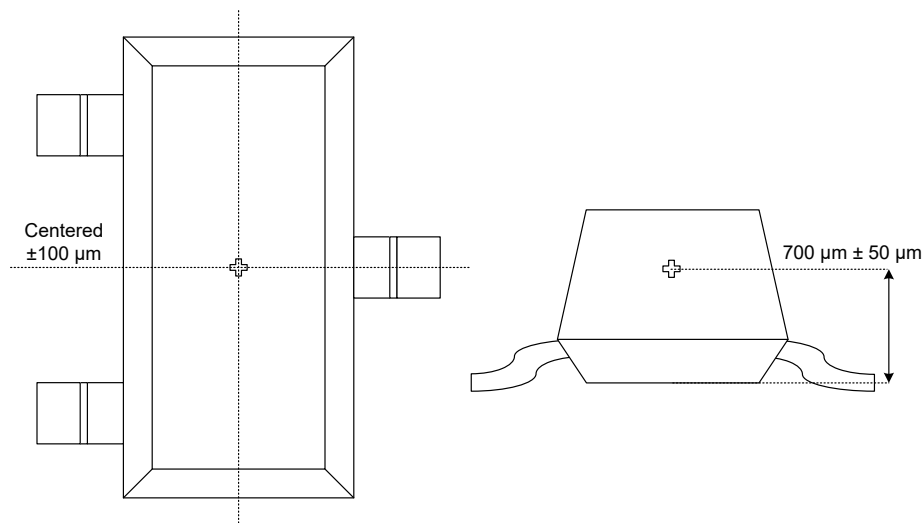


图 9-1. Hall Sensor Location (Not to Scale)

9.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 [通知](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

9.3 支持资源

TI E2E™ 中文支持论坛 是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [使用条款](#)。

9.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

9.5 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

9.6 术语表

TI 术语表

本术语表列出并解释了术语、首字母缩略词和定义。

10 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision A (February 2023) to Revision B (August 2024)	Page
• 删除了测量单位和值之间的空格.....	1
• 将 器件信息 表更改为 封装信息	1
• Changed the typical threshold and typical hysteresis values in the <i>Device Comparison</i> table to correctly match the values found in the <i>Magnetic Characteristics</i> table.....	3

Changes from Revision * (December 2022) to Revision A (February 2023)	Page
• Added <i>Device Comparison</i> table.....	3
• Added TMAG5115A magnetic specifications.....	5
• Added typical characteristic curves for TMAG5115A.....	6

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMAG5115A1CQDBZR	Active	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	15A1
TMAG5115A1CQDBZR.A	Active	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	15A1
TMAG5115B1CQDBZR	Active	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	15B1
TMAG5115B1CQDBZR.A	Active	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	15B1

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

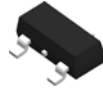
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TMAG5115A1CQDBZR	SOT-23	DBZ	3	3000	178.0	9.0	3.15	2.77	1.22	4.0	8.0	Q3
TMAG5115B1CQDBZR	SOT-23	DBZ	3	3000	178.0	9.0	3.15	2.77	1.22	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS

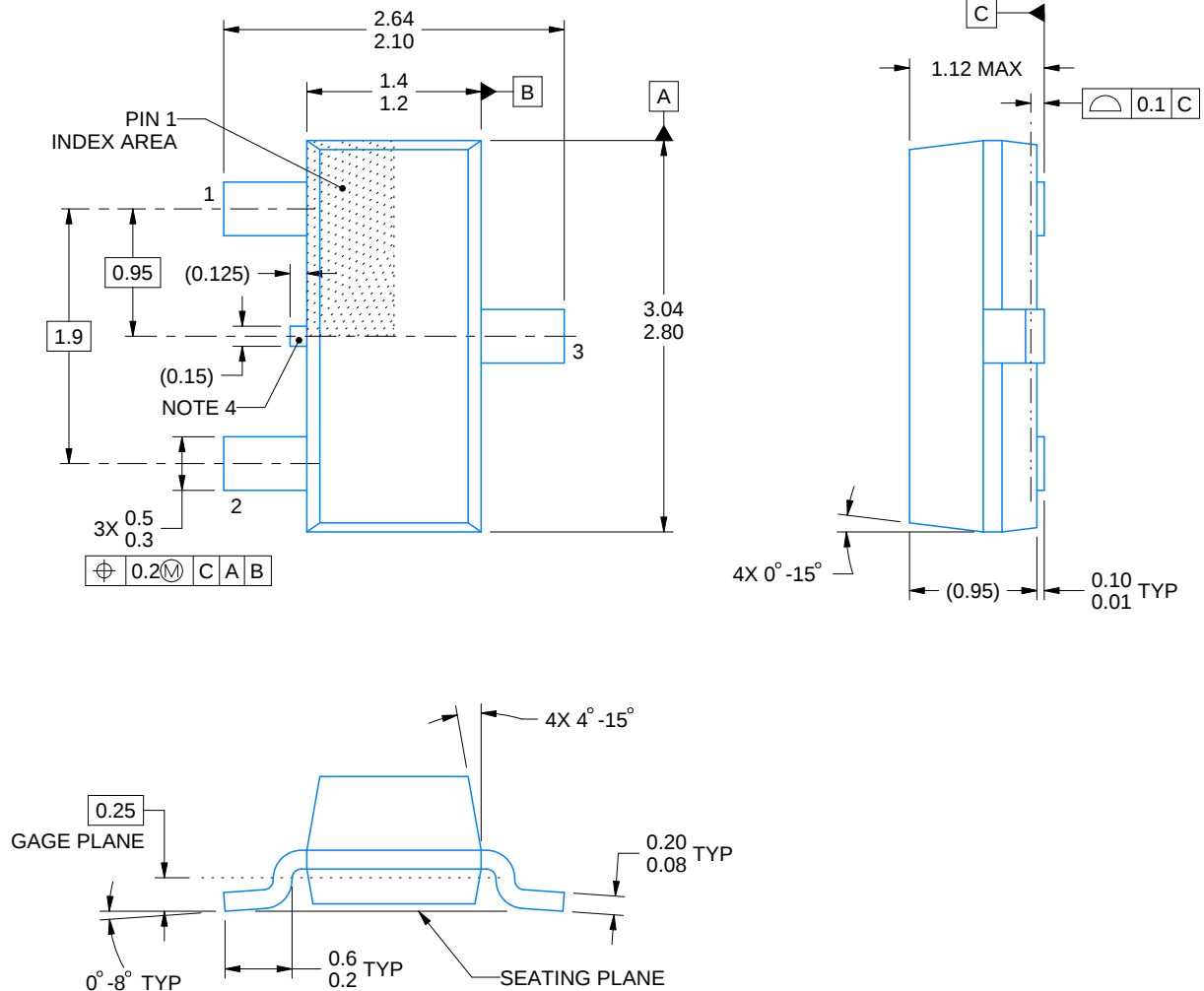


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TMAG5115A1CQDBZR	SOT-23	DBZ	3	3000	180.0	180.0	18.0
TMAG5115B1CQDBZR	SOT-23	DBZ	3	3000	180.0	180.0	18.0

DBZ0003A**PACKAGE OUTLINE****SOT-23 - 1.12 mm max height**

SMALL OUTLINE TRANSISTOR



4214838/F 08/2024

NOTES:

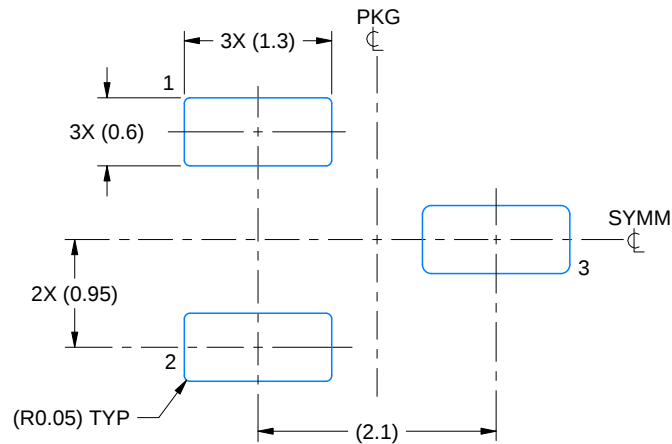
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-236, except minimum foot length.
4. Support pin may differ or may not be present.
5. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

EXAMPLE BOARD LAYOUT

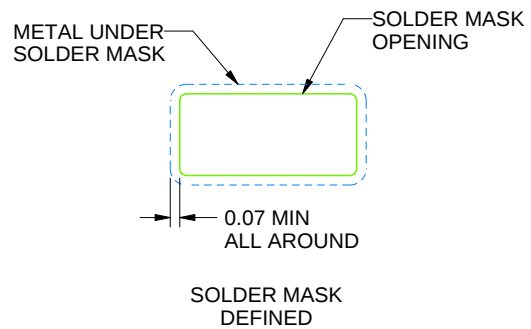
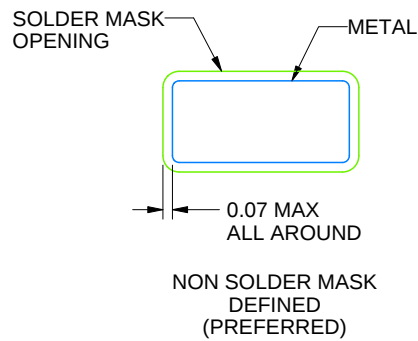
DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
SCALE:15X



SOLDER MASK DETAILS

4214838/F 08/2024

NOTES: (continued)

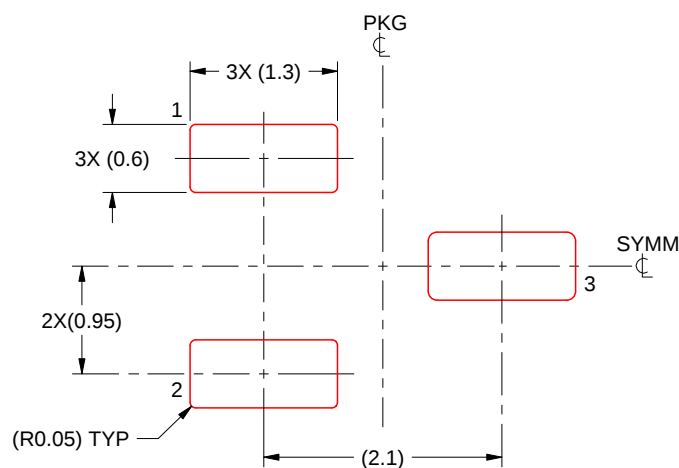
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:15X

4214838/F 08/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

重要通知和免责声明

TI“按原样”提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做任何明示或暗示的担保，包括但不限于对适销性、某特定用途方面的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他功能安全、信息安全、监管或其他要求。

这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的相关应用。严禁以其他方式对这些资源进行复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。您应全额赔偿因在这些资源的使用中对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，TI 对此概不负责。

TI 提供的产品受 [TI 的销售条款](#) 或 [ti.com](#) 上其他适用条款/TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
版权所有 © 2025，德州仪器 (TI) 公司